



**HEAT TRANSFER SIMULATION OF CPU WITH RESPECT TO HEAT  
GEOMETRY COMPONENTS**

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## **ABSTRACT**

This study investigates the heat transfer simulation in a central processing unit (CPU) with respect to heat geometry components. The STAR-DESIGN of the well-known computational fluid dynamics (CFD) was employed in order to simulate the dissipative heat transfer in a ventilated enclosure. A complete computer chassis model with heat sinks and fans inside the CPU was created using CATIA. The simulation approach for the full computer chassis model consists of these following objects; CPU, CPU heat sink, CPU fan, AGP graphic card, AGP heat sink and fan, chipset, mainboard, RAM, power supply, grilles, floppy and hard drives. The selected application is the CPU cooling of a standard desktop personal computer. The CPU in a desktop must be cooled to limit its temperature to the manufacturer's maximum allowed value. The CPU is cooled using an attached heat sink with the heat rejected to air supply by a fan. The parameter that taken into consideration in this thesis is focused on the heat sinks where three different heat sinks modelled into full chassis to computationally simulated and analyzed so that the thermal performance can be improved. The result from the simulation analysis showed the average temperature and velocity inside the CPU and from that the best model of CPU can be obtained.

## **TABLE OF CONTENTS**

<b>CONTENTS</b>	<b>PAGE</b>
ACKNOWLEDGEMENT	i
ABSTRACT	iii
TABLE OF CONTENTS	iv
LIST OF TABLES	vii
LIST OF FIGURES	viii
LIST OF ABBREVIATIONS	ix

### **CHAPTER 1:PROJECT OVERVIEW**

1.1	Introduction	1
1.2	Background of project	5
1.3	Objectives of project	6
1.4	Significances of project	6
1.5	Scopes of project	6
1.6	Methodology of project	7

### **CHAPTER 2:LITERATURE REVIEW**

2.1	Previous researchers	8
2.2	Computer chassis model	10
2.3	Boundary conditions	14

## **CHAPTER 3:THEORITICAL BACKGROUND**

3.1.	History of Computational Fluid Dynamics	16
3.2.	Introduction of Computational Fluid Dynamics	18
3.3.	Heat Transfer Mechanism	19
3.3.1	Conduction	20
3.3.2	Convection	21
3.3.3	Radiation	22
3.4.	Steady and Unsteady Flow	23
3.5.	Compressible and Incompressible Flow	23
3.6.	Laminar and Turbulent Flow	24
3.7.	Turbulent Model	24
3.7.1	Standard and Realizable K- $\epsilon$ Model	25
3.8.	Computational Fluid Dynamics	27
3.8.1	Mesh Solver	27
3.8.2	The Solver	28
3.8.3	Governing Equations	29

## **CHAPTER 4:METHODOLOGY**

4.1.	Introduction	31
4.2.	CATIA Model Generation	32
4.3.	CFD Analysis	35
4.4.	Boundary Condition and Flow Properties	37
4.5.	Mesh Generation	42

## **CHAPTER 5:RESULTS AND DISCUSSION**

5.1.	Temperature Distribution	46
5.2.	Temperature Analysis of CPU and Chip	46
5.3.	Velocity Analysis of CPU and Chip	49
5.4.	The Average Temperature and Velocity in the CPU	54
5.5.	Convection Heat Transfer of Heat Generating Components	56